



## NEW DRAWING SHEET

CREATING A WEAKENED ZONE IN A  
WAFER TO DEFINE THE LAYER TO BE  
DETACHED AND A REMAINDER  
PORTION OF THE WAFER SUCH THAT  
THE WEAKENED ZONE INCLUDES A  
MAIN REGION AND A LOCALIZED  
SUPER-WEAKENED REGION THAT IS  
MORE WEAKENED THAN THE MAIN  
REGION



INITIATING DETACHMENT OF THE  
LAYER FROM THE REMAINDER  
PORTION OF THE WAFER AT THE  
SUPER-WEAKENED REGION BY  
APPLYING A CONTROLLED  
DETACHMENT FORCE OBTAINED BY  
HEATING AT LEAST THE WEAKENED  
ZONE

FIGURE 4